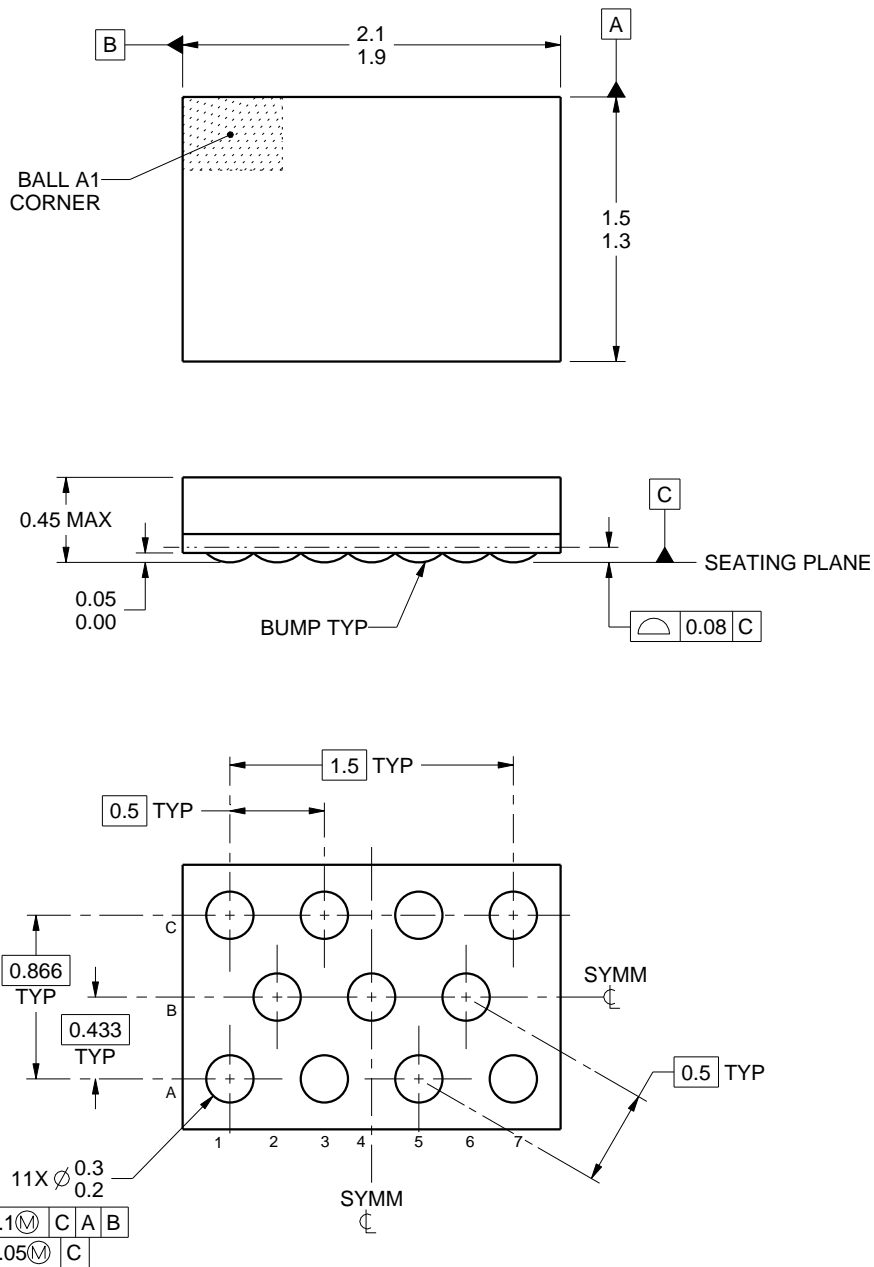


PACKAGE OUTLINE

ZSU0011A

MicroStar CSP™ - 0.45 mm max height

MICRO CHIP SCALE PACKAGE



4220297/B 07/2016

NOTES:

MicroStar CSP is a trademark of Texas Instruments

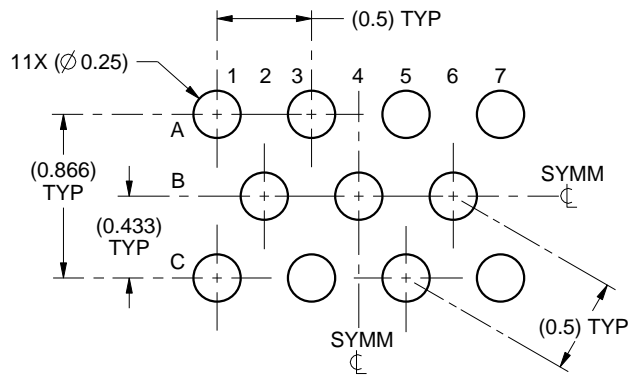
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

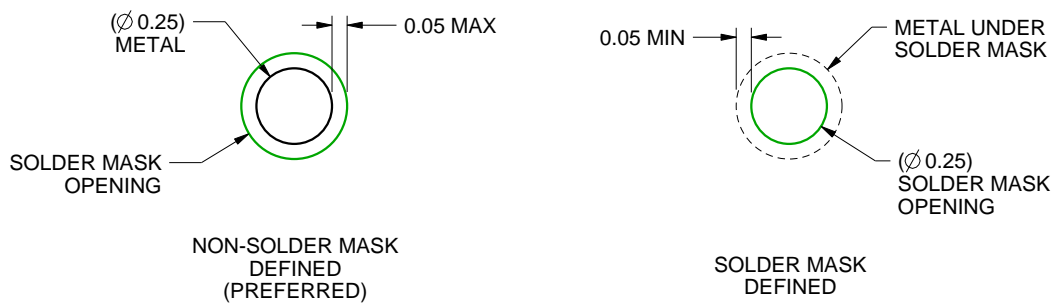
ZSU0011A

MicroStar CSP™ - 0.45 mm max height

MICRO CHIP SCALE PACKAGE



LAND PATTERN EXAMPLE
SCALE:25X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

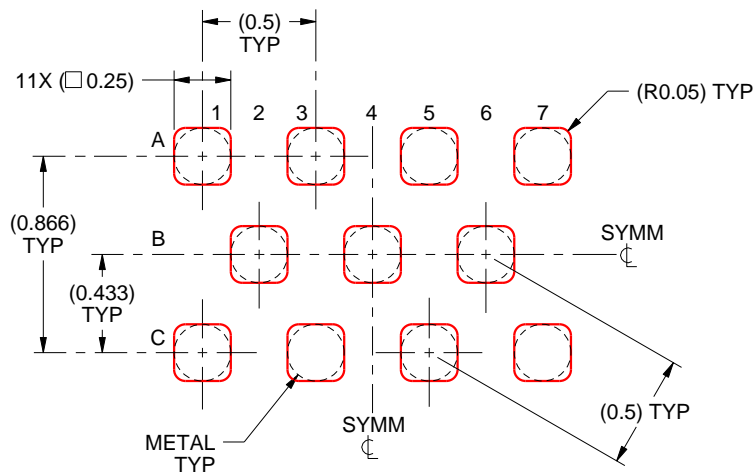
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

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MICRO CHIP SCALE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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